

Gap Pad® 1500R

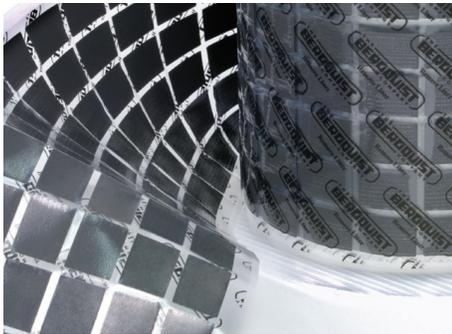
July 2011

PRODUCT DESCRIPTION

Thermally Conductive, Reinforced Gap Filling Material

FEATURES AND BENEFITS

- Thermal conductivity: 1.5 W/m-K
- Fiberglass reinforced for puncture, shear and tear resistance
- Easy release construction
- Electrically isolating



Gap Pad® 1500R has the same highly conformable, low-modulus polymer as the standard Gap Pad® 1500. The fiberglass reinforcement allows for easy material handling and enhances puncture, shear and tear resistance. The natural tack on both sides of the material allows for good compliance to mating surfaces of components, further reducing thermal resistance.

Note: To build a part number, visit our website at www.bergquistcompany.com.

TYPICAL PROPERTIES OF GAP PAD 1500R

PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color	Black	Black	Visual
Reinforcement Carrier	Fiberglass	Fiberglass	—
Thickness (inch) / (mm)	0.010 to 0.020	0.254 to 0.508	ASTM D374
Inherent Surface Tack (1 side)	2	2	—
Density (Bulk Rubber) (g/cc)	2.1	2.1	ASTM D792
Heat Capacity (J/g-K)	1.3	1.3	ASTM E1269
Hardness (Bulk Rubber) (Shore 00) (1)	40	40	ASTM D2240
Young's Modulus (psi) / (kPa) (2)	45	310	ASTM D575
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	—
ELECTRICAL			
Dielectric Breakdown Voltage (Vac)	>6000	>6000	ASTM D149
Dielectric Constant (1000 Hz)	6.0	6.0	ASTM D150
Volume Resistivity (Ohm-meter)	10 ¹¹	10 ¹¹	ASTM D257
Flame Rating	V-O	V-O	U.L. 94
THERMAL			
Thermal Conductivity (W/m-K)	1.5	1.5	ASTM D5470
THERMAL PERFORMANCE vs. STRAIN			
	Deflection (% strain)		
	10	20	30
Thermal Impedance (°C-in ² /W) 0.020" (3)	1.07	0.88	0.82

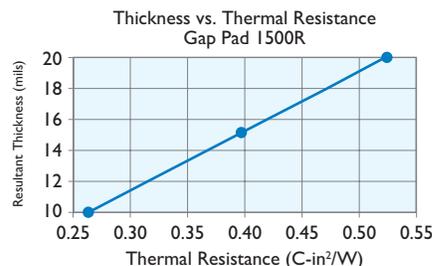
1) Thirty second delay value Shore 00 hardness scale. 2) Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch². 3) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

TYPICAL APPLICATIONS INCLUDE

- Telecommunications
- Computer and peripherals
- Power conversion
- RDRAM™ memory modules/chip scale packages
- Areas where heat needs to be transferred to a frame chassis or other type of heat spreader

CONFIGURATIONS AVAILABLE

- Sheet form, die-cut parts, and roll form (converted or unconverted)



Disclaimer

Note:

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